



Material Content Data Sheet



Sales Product Name				IPD30N03S2L-10		Issued		22. January 2018	
MA#				MA001913470					
Package				PG-TO252-3-11		Weight*		370.56 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.654	0.72	0.72	7163	7163	
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174		
	non noble metal	iron	7439-89-6	0.215	0.06		581		
	non noble metal	copper	7440-50-8	215.017	58.02	58.10	580247	581002	
	non noble metal	aluminium	7429-90-5	1.159	0.31	0.31	3127	3127	
wire	non noble metal	aluminium	7429-90-5	1.159	0.31	0.31	3127	3127	
encapsulation	organic material	carbon black	1333-86-4	1.260	0.34		3401		
	plastics	epoxy resin	-	22.057	5.95		59523		
	inorganic material	silicondioxide	60676-86-0	102.722	27.72	34.01	277206	340130	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10093	10093	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	245	246	
solder	non noble metal	tin	7440-31-5	0.048	0.01		128		
	noble metal	silver	7440-22-4	0.059	0.02		160		
	non noble metal	lead	7439-92-1	2.272	0.61	0.64	6131	6419	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		16		
	non noble metal	iron	7439-89-6	0.019	0.01		52		
	non noble metal	copper	7440-50-8	19.177	5.18	5.19	51752	51820	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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